

Method for Bonding of Chips on Wafers

Abstract

Method for bonding of a plurality of chips (3) onto a base wafer (1) which contains chips (3') on the front, the chips (3) being stacked in at least one layer on the back of the base wafer (1) and electrically conductive connections (7) are established between the vertically adjacent chips (3, 3'), with the following steps:

- a) fixing of the front (2) of the base wafer (1) on a carrier (5),
 - b) placing at least one layer of chips (3) in defined positions on the back (6) of the base wafer (1), and
 - c) heat treatment of the chips (3, 3') on the base wafer (1) fixed on the carrier (5),
- characterized in that prior to step c) at least partial separation of the chips (3') of the base wafer (1) into separated chip stack sections (1c) of the base after (1) takes place.

Figure 1